

1310TX DFB 1550RX PD BOSA 2GHz CATV Transmission

HETRPD32xxx510MxxxxG

Features:

- Coaxial Package
- ♦ InGaAsP/InP MQW-DFB Laser Diode
- Low threshold, high slope efficiency and high output power
- ◆ Data Rate up to 2.5G
- ◆ Single-mode fiber pigtailed with SC FC ST or LC connector
- High channel isolation
- Low return loss
- Optional with Isolator
- ◆ Operating Case Temperature: -20°C to +85°C
- RoHS Compliant Products Available

Applications:

- ◆ Long distance digital transmission system
- Cable television system
- WDM systems

Absolute Maximum Ratings:*Note1

Parameter	Symbol	Ratings	Unit
Storage Temperature	Tstg	-40~+85	$^{\circ}$
Operating Case Temperature	Тор	-20~+85	$^{\circ}$
Reverse Voltage (Monitor PD)	V_{RD}	20	V
Photodiode Forward Current (Monitor PD)	I _{FD}	2	mA
Lead Soldering (Temperature)/(Time)		260/10	℃/Sec
Reverse Voltage (Analog PD)	Vrpd	30	V
Forward Current (Analog PD)	Ifpd	10	mA

^{*}Note1: Exceeding any one of these values may destroy the device immediately.

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Electrical and Optical Characteristics – Transmitter:

(If=Ith+20mA, Pf=1mW, SMF (9.5/125µm), Tc=+25+/-2°C, unless otherwise noted.)

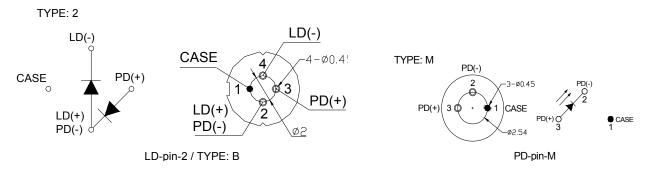
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Threshold Current	lth	at Tc=25±3℃		10	15	mA
Output Power (After coupled)	Pf	CW, lop=lth+20mA	1.0	-	2.99	mW
Slope Efficiency	Se	CW, Average	0.05		0.15	mW/mA
Operating Voltage	Vop	CW, lop=Ith+20mA		1.1	1.6	V
Peak Wavelength	λς	CW, lop=Ith+20mA, Tc= -20~85°C	1290	1310	1330	nm
Side Mode Suppression Ratio	SMSR	CW, lop=lth+20mA, Tc= -20~85°C	35	40		dB
Monitor Current	lmon	CW, lop=lth+20mA	0.1		1.0	mA
Monitor Dark Current	ld	VRD=5V			0.1	μA
Relative intensity Noise					-145	dB/Hz
Optical Isolation	Iso		30			dB
Tracking Error	TE	APC,-20℃~+85℃	-1.5		1.5	dB
Rise/Fall Time	Tr/Tf	lb=lth, 20~80%		0.1	0.15	ns

Electrical / Optical Specifications – Receiver:

Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit	
Operating Wavelength*Note2	λ		1500	1550	1600	nm	
Active Area	Ф			75		μm	
-3dBm Bandwidth	BW	VR = 5V	2			GHz	
Dark Current	ld	VR = 5V			1.0	nA	
Responsivity	R	λ=1550nm		0.80		A/W	

^{*}Note2: Receiver Operating Wavelength can be customized.

Pin Assignment: *Note3

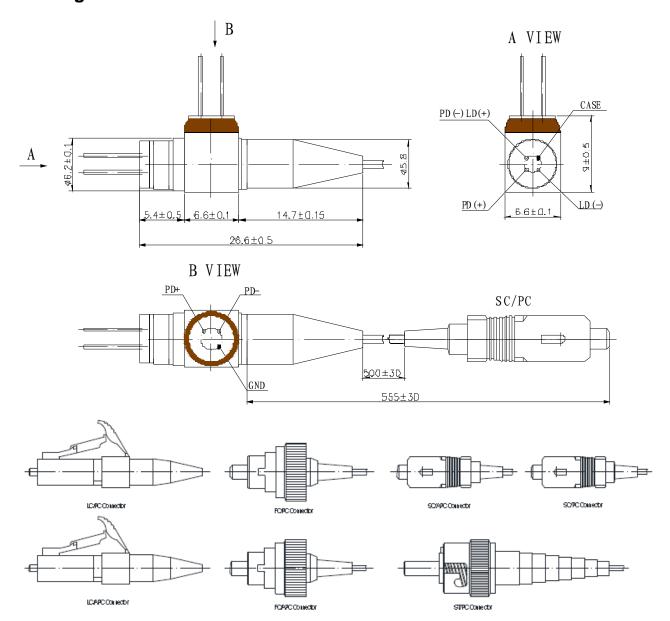


*Note3: Pin assignment can be customized.

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Package Dimension: *Note4



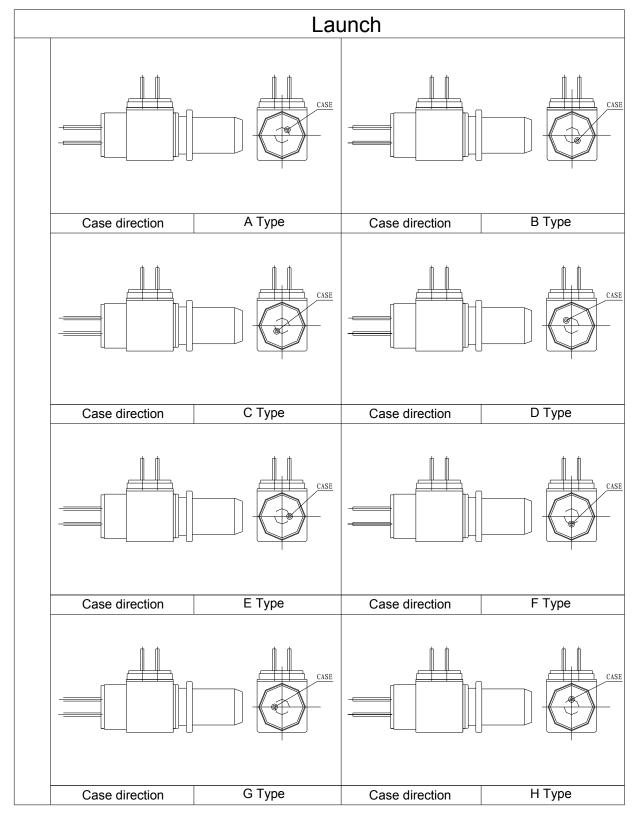
*Note4: PIN direction and laser mark can be customized

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TX Pin Order Code:*Note5, 6, 7



Note5. This picture is for pluggable, pigtail BIDI chip PIN package direction's reference.

Note6. This picture is suitable for RX Pin direction comparison .

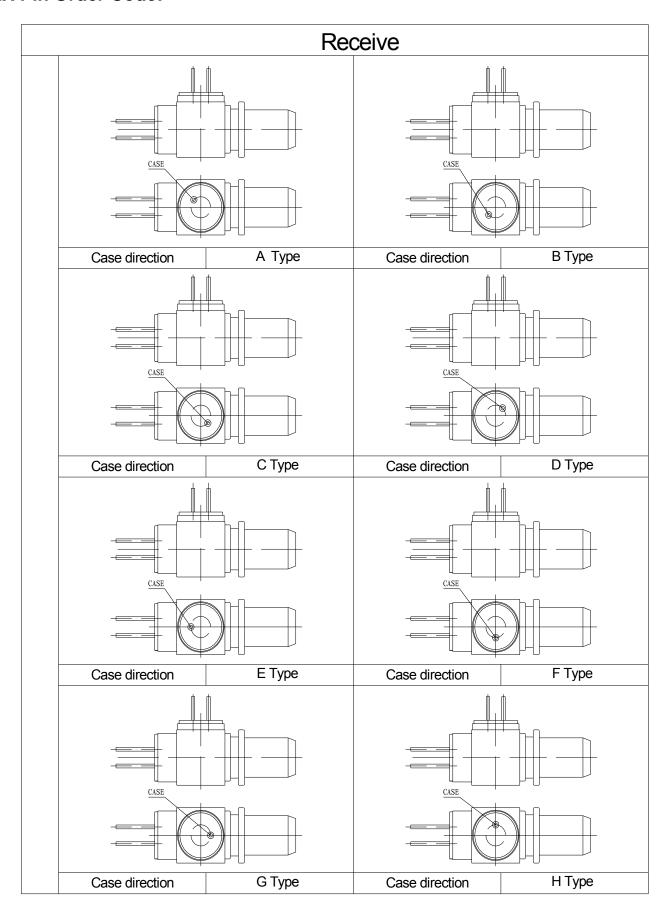
Note7. The package direction is described as "x-x" For example "A-B", "A" is TX chip Pin direction, "B" is RX chip Pin direction.

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RX Pin Order Code:



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Nomenclature:

HEBIDI	<u> </u>												
	Α	В	C	D	F	F	G	Н	1	.I.	K	1	М

Code	Parameter	Detailed Description									
Α	Laser Type	D=DFB LD									
В	Launch Wavelength	3=1310nm									
С	Launch Data Rate		1=	1.250	G			2=	2.5G		
D	Output Power		10=1~	-1.99)mW	1		20=2.0	~2.99m\	٧	
Е	Receiver Wavelength					5=15	50nm				
F	Active Diameter		1=75um								
G	Bandwidth	0≤2GHz			1≤2.5		GHz		2≤3.2GHz		
Н	Connector	F=F	C/PC	S= SC/PC		C/PC	T=ST/PC		L=LC/PC		
	Connector	SA= SC/APC		F/	FA=FC/APC		LA=LC/APC		BLANK =None		
I	TX Pin Package Direction	Α	В	C)	D	Е	F	G	Н	
J	RX Pin Package Direction	A B C			D	Е	F	G	Н		
K	RX TO Insulated With Shell	Blank= Insulation				N=NO Insulation					
L	Isolator	Blank=None					G=with I				
М	Fiber Length	Blank=50cm 035=35ci				35=35cm	100	=100cm	XXX=	XXX=Custom	

Precaution:

- (1) The modules should be handled in the same manner as ordinary semiconductor devices to prevent the electro-static damages. For safe keeping and carrying, the modules should be packaged with ESD proof material. To assemble the modules on PCB, the workbench, the soldering iron and the human body should be grounded.
- (2) Please pay special attention to the atmosphere condition because the dew on the module may cause some electrical damages.
- (3) Under such a strong vibration environment as in automobile, the performance and reliability are not guaranteed.

Notice:

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